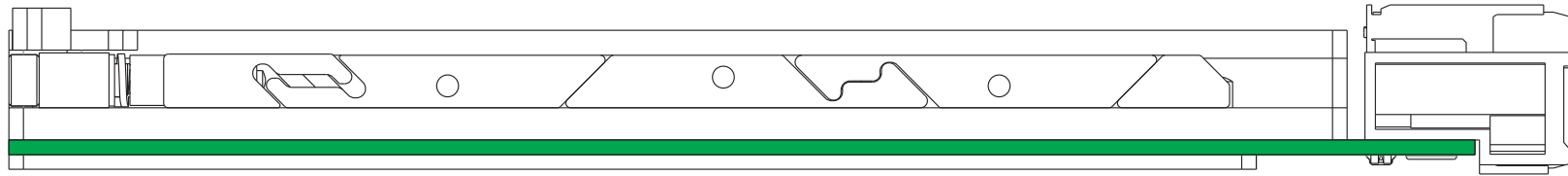
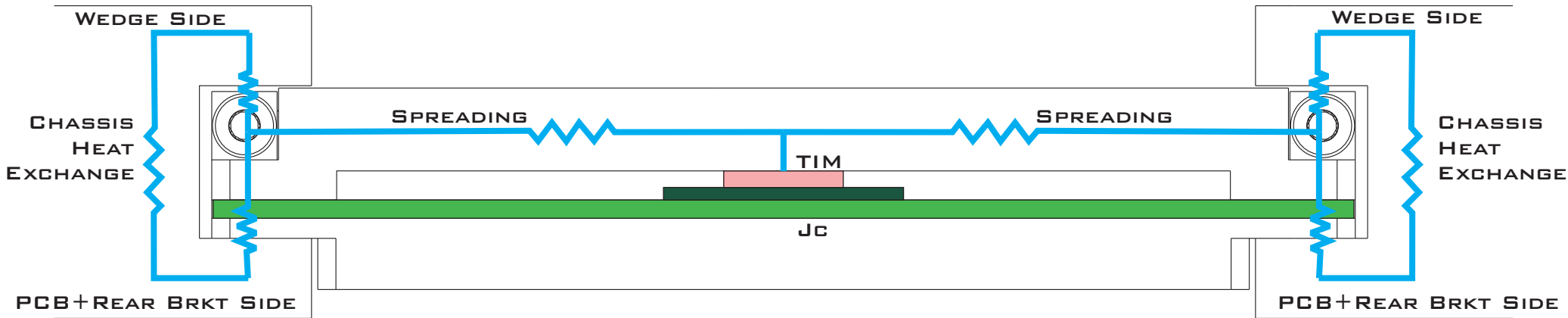


# PRIMARY SIDE WEDGE LOCKS



PCB RESIDES IN COLDWALL THERMAL PATH  
CONVECTION FRONT PANEL HOLES REMAIN IN PCB



$$\theta_{(COLDWALL)} = \frac{(\theta_{(WEDGE\ SIDE)} \times (\theta_{(PCB)} + \theta_{(REAR\ BRKT)}))}{(\theta_{(WEDGE\ SIDE)} + \theta_{(PCB)} + \theta_{(REAR\ BRKT)})}$$

$$\theta_{(COLDWALL)} = \frac{(.76C^{\circ}/W \times (2.0C^{\circ}/W + .05C^{\circ}/W))}{(.76C^{\circ}/W + 2.05C^{\circ}/W)}$$

$$\theta_{(COLDWALL)} = \sim 0.55 C^{\circ}/W \text{ PER EDGE}$$

$$\theta_{(COLDWALL)} = \sim 0.28 C^{\circ}/W$$

## THERMAL RESISTANCE VLAUES!

WEDGE SIDE = 0.76 C°/W

\* PCB (.063") = 2.0 C°/W

\*\* REAR FRAME = .05 C°/W

\* ESTIMATED USING PCB  
THRU PLANE CONDUCTIVITY  
OF 0.75 W/MK.

\*\* ESTIMATED USING AL6061  
THERMAL CONDUCTIVITY

2 EDGES PER CARD